

HSC285

Silicon Schottky Barrier Diode for High frequency detection

REJ03G0011-0100Z

Rev.1.00

Apr.16.2003

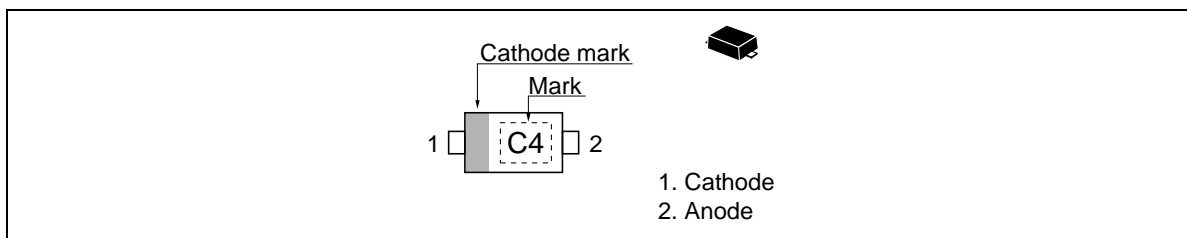
Features

- Low forward voltage, Low capacitance and High detection sensitivity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSC285	C4	UFP

Pin Arrangement



HSC285

Absolute Maximum Ratings

(T_a = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	2	V
Average rectified current	I _O	5	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics

(T_a = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V _{F1}	—	—	0.15	V	I _F = 0.1 mA
	V _{F2}	—	—	0.27		I _F = 1 mA
Capacitance	C	—	0.3	—	pF	V _R = 1 V, f = 1 MHz
ESD-Capability *1	—	10	—	—	V	C = 200 pF, R _L = 0 Ω, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ; I_R > 100 μA at V_R = 0.5 V

Main Characteristic

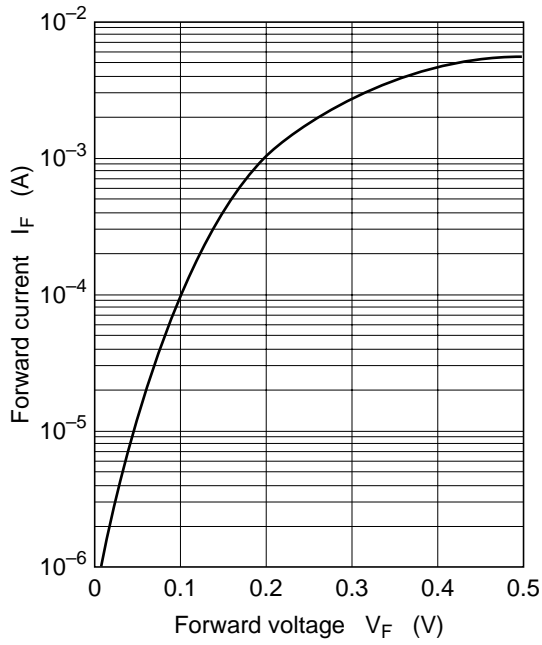


Fig.1 Forward current vs. Forward voltage

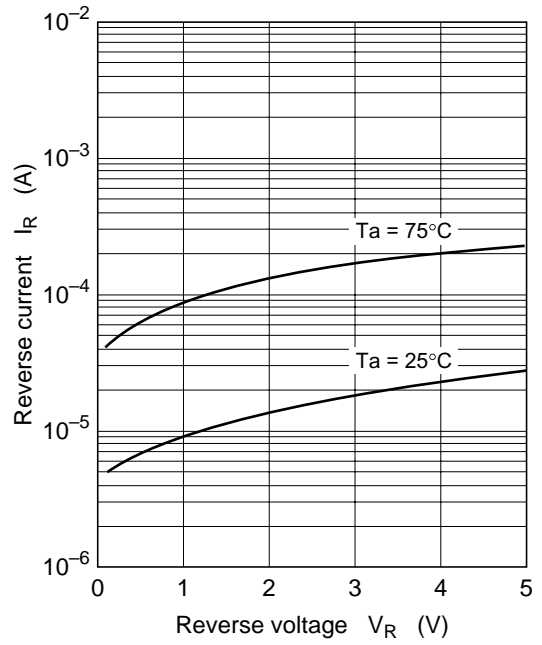


Fig.2 Reverse current vs. Reverse voltage

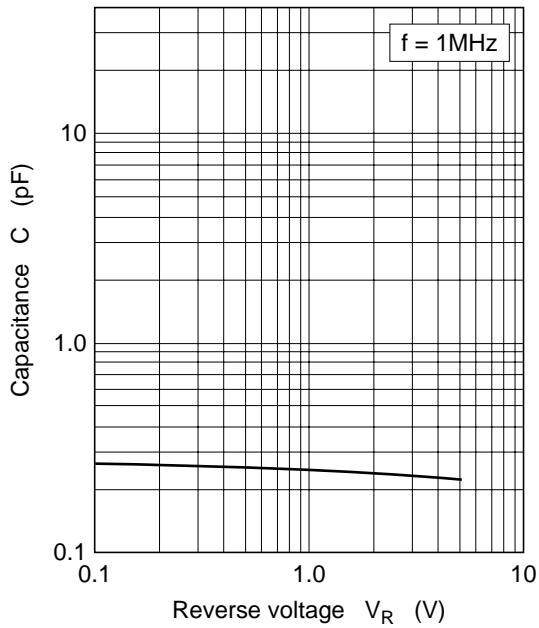
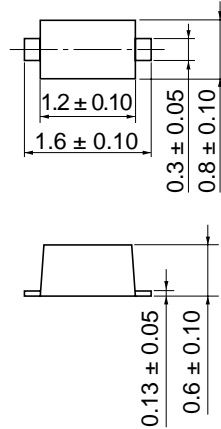


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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